

Plaskon LS-16

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is a low stress molding compound specifically formulated for use with automated molding equipment to increase semiconductor manufacturing productivity and reduce production costs. This compound is recommended for molding of stress sensitive DIPs, SOICs, PLCCs and small QFPs.

General Information			
Features	Semi-conductive		
	Low viscosity		
	Fast molding cycle		
	Fast curing		
	Good formability		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.83	g/cm ³	ASTM D792
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus	1.17	MPa	ASTM D790
Flexural Strength	0.0110	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	152	°C	ASTM E1356
CLTE - Flow	1.7E-5	cm/cm/°C	ASTM D696
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	9.5E+15	ohms · cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	3.30		ASTM D150
Dissipation Factor (1 kHz)	3.0E-3		ASTM D150
Arc Resistance	180	sec	ASTM D495
Flammability	Nominal Value	Unit	Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	30	%	ASTM D2863
Additional Information			

Recommended Storage Temperature: 5°C Life @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 months Life @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 days Life @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 days Spiral Flow, 175°C, 1000 psi: 51 cm Automatic Orifice Viscosity, 165°C, Shear Rate is 68000 sec-1, 1 mm die length, 1/2 mm diameter: 18 Pascal sec Ram Follower Gel Time, 165°C, 1000 psi: 14 sec Ash Content: 74.2 % Hydrolyzable Halides: <1 ppm Cull Hot Hardness, Shore D, 75 sec, 165°C: 80 Arc Resistance, 110v AC 180 sec The following information was transfer molded and post cured for 2 hours at 165°C

Glass Transition Temperature Tg: 162°C

Linear Thermal Expansion, Alpha 1: 15.9 cm⁻⁶/cm/°C

Linear Thermal Expansion, Alpha 2: 66 cm⁻⁶/cm/°C

The following information was transfer molded and post cured for 2 hours at 175°C

Glass Transition Temperature Tg: 165°C

Linear Thermal Expansion, Alpha 1: 15.6 cm⁻⁶/cm/°C

Linear Thermal Expansion, Alpha 2: 67 cm⁻⁶/cm/°C

Thermal Conductivity 15.7 cal/cm-sec-°C

The following information was transfer molded and post cured for 4 hours at 165°C

Glass Transition Temperature Tg: 150°C

Linear Thermal Expansion, Alpha 1: 16.7 cm⁻⁶/cm/°C

Linear Thermal Expansion, Alpha 2: 61 cm⁻⁶/cm/°C

The following information was transfer molded and post cured for 4 hours at 175°C

Glass Transition Temperature Tg: 152°C

Linear Thermal Expansion, Alpha 1: 17.4 cm⁻⁶/cm/°C

Linear Thermal Expansion, Alpha 2: 64 cm⁻⁶/cm/°C

The following information was transfer molded and post cured for 15 minutes at 165°C

Glass Transition Temperature Tg: 160°C

Linear Thermal Expansion, Alpha 1: 16.5 cm⁻⁶/cm/°C

Linear Thermal Expansion, Alpha 2: 65 cm⁻⁶/cm/°C

The following information was transfer molded and post cured for 15 minutes at 175°C

Glass Transition Temperature Tg: 162°C

Linear Thermal Expansion, Alpha 1: 17.4 cm⁻⁶/cm/°C

Linear Thermal Expansion, Alpha 2: 67 cm⁻⁶/cm/°C

Injection instructions

Auto Resin Transfer Molding:

Molding Temperature: 165 to 175°C

Molding Pressure: 500 to 1000 psi

Cycle Time, 175°C: 30 to 40 sec

Cycle Time, 165°C: 40 sec

Post Mold Cure Time, 175°C: 0 to 15 hr

Post Mold Cure Time, 165°C: 0 to 15 hr

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